

P-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ.)
- 200	2.35 at $V_{GS} = - 10$ V	- 0.49	8.0
	2.45 at $V_{GS} = - 6.0$ V	- 0.48	

FEATURES

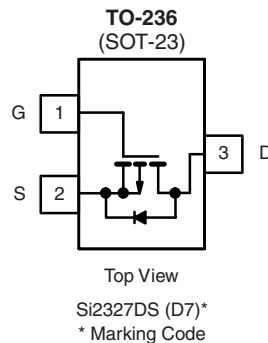
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- Ultra Low On-Resistance
- Small Size



RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

- Active Clamp Circuits in DC/DC Power Supplies



Ordering Information: Si2327DS -T1-E3 (Lead (Pb)-free)
Si2327DS -T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	- 200		V
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current ($T_J = 150\text{ }^{\circ}\text{C}$) ^{a, b}	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	- 0.49	- 0.38	A
	$T_A = 70\text{ }^{\circ}\text{C}$		- 0.39	- 0.31	
Pulsed Drain Current		I_{DM}	- 1.0		
Continuous Source Current (Diode Conduction) ^{a, b}		I_S	- 1.0	- 0.6	
Single Pulse Avalanche Current	L = 1.0 mH	I_{AS}	4.0		
Single Pulse Avalanche Energy		E_{AS}	0.8		
Maximum Power Dissipation ^{a, b}	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	1.25	0.75	W
	$T_A = 70\text{ }^{\circ}\text{C}$		0.8	0.48	
Operating Junction and Storage Temperature Range		T_J, T_{stq}	- 55 to 150		$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	75	100	°C/W
		120	166	
Maximum Junction-to-Foot (Drain)	R_{thJF}	40	50	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Pulse width limited by maximum junction temperature.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Limits			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = - 250 μA	- 200			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 2.5		- 4.5	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 200 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 200 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 15 V, V _{GS} = 10 V	- 1.0			A
Drain-Source On-Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 0.5 A		1.9	2.35	Ω
		V _{GS} = - 6.0 V, I _D = - 0.5 A		1.96	2.45	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 15 V, I _D = - 0.5 A		1.8		S
Diode Forward Voltage	V _{SD}	I _S = - 1.0 A, V _{GS} = 0 V		- 0.85	- 1.2	V
Dynamic ^b						
Total Gate Charge	Q _g	V _{DS} = - 100 V, V _{GS} = 10 V I _D ≅ - 0.5 A		8.0	12	nC
Gate-Source Charge	Q _{gs}			1.3		
Gate-Drain Charge	Q _{gd}			2.5		
Gate Resistance	R _g	f = 1.0 MHz		8.0		Ω
Input Capacitance	C _{iss}	V _{DS} = - 25 V, V _{GS} = 0 V, f = 1 MHz		340	510	pF
Output Capacitance	C _{oss}			25		
Reverse Transfer Capacitance	C _{rss}			14		
Switching ^c						
Turn-On Time	t _{d(on)}	V _{DD} = - 100 V, R _L = 100 Ω I _D ≅ - 1.0 A, V _{GEN} = - 10 V R _g = 6 Ω		8	12	ns
	t _r			11	17	
Turn-Off Time	t _{d(off)}			16	25	
	t _f			11	17	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 0.5 A, dI/dt = 100 A/μs		140	200	nC

Notes:

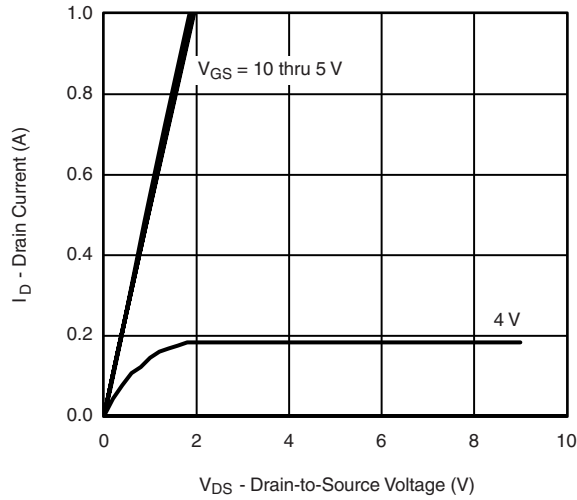
a. Pulse test: $PW \leq 300\text{ }\mu\text{s}$ duty cycle $\leq 2\%$.

b. For DESIGN AID ONLY, not subject to production testing.

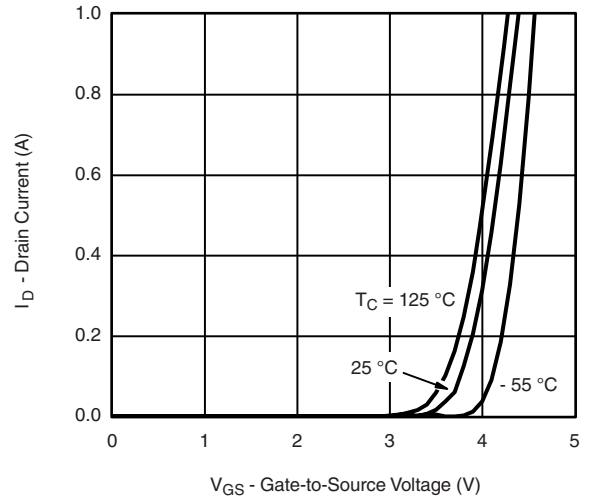
c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

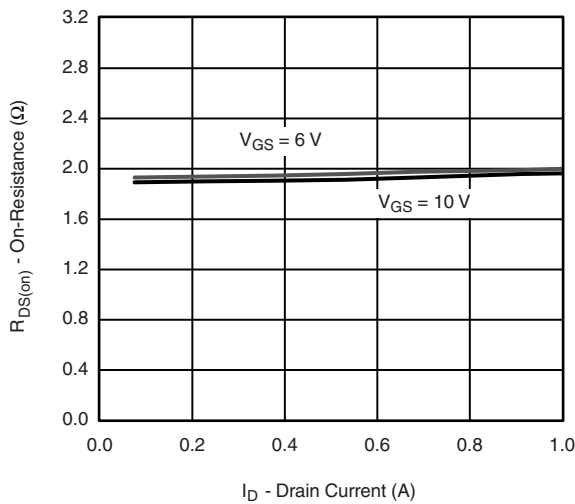
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



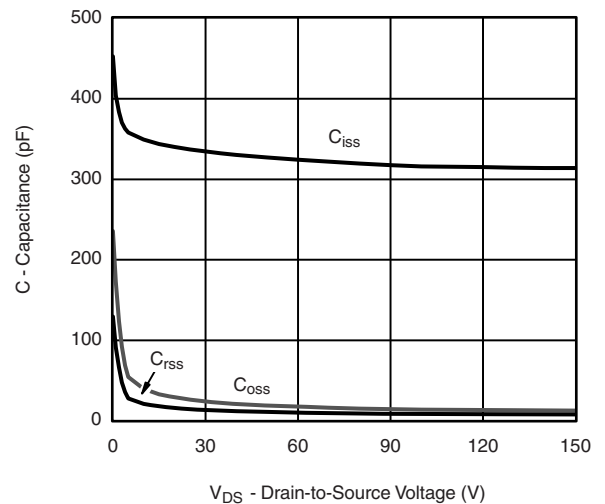
Output Characteristics



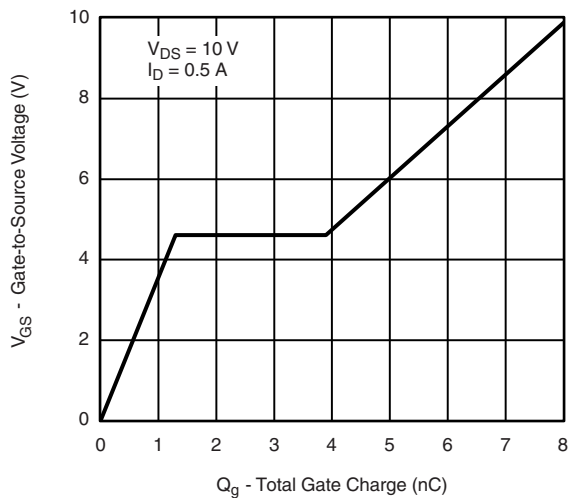
Transfer Characteristics



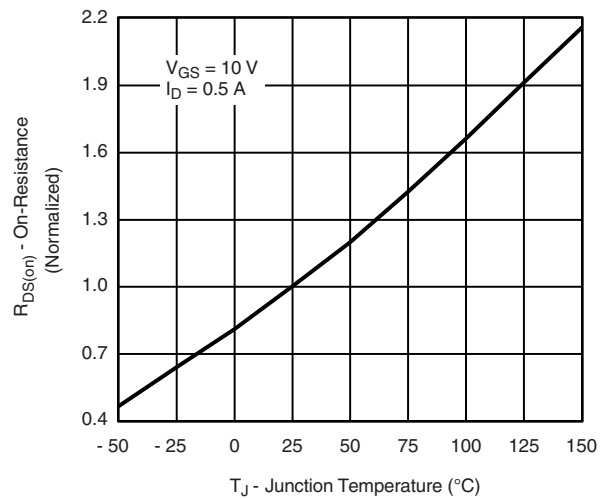
On-Resistance vs. Drain Current



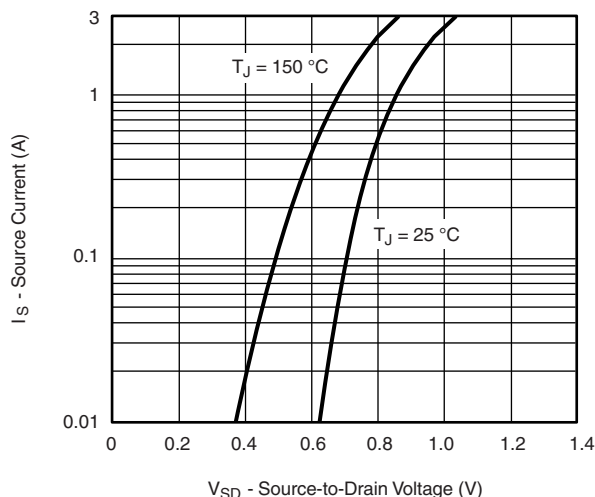
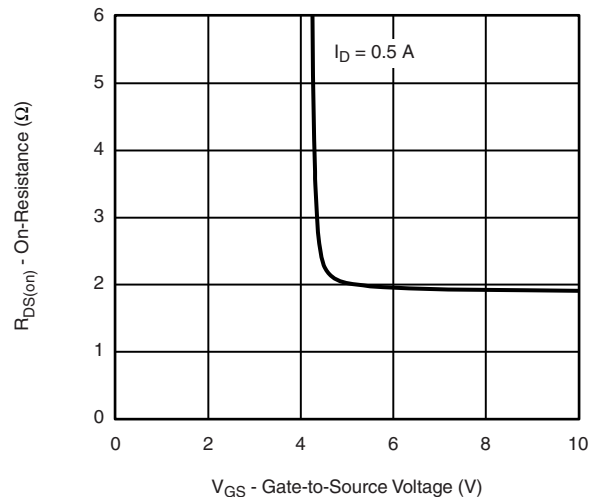
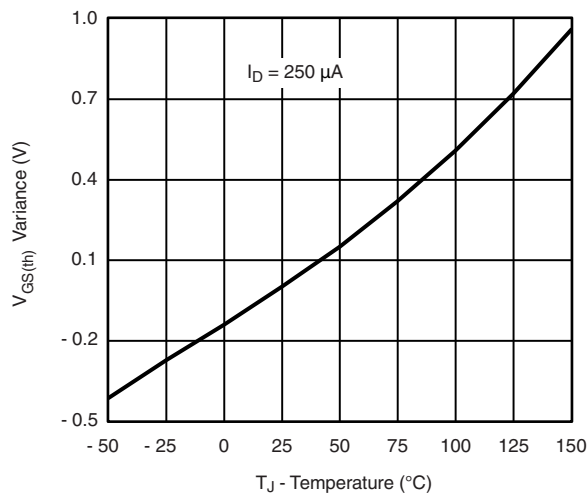
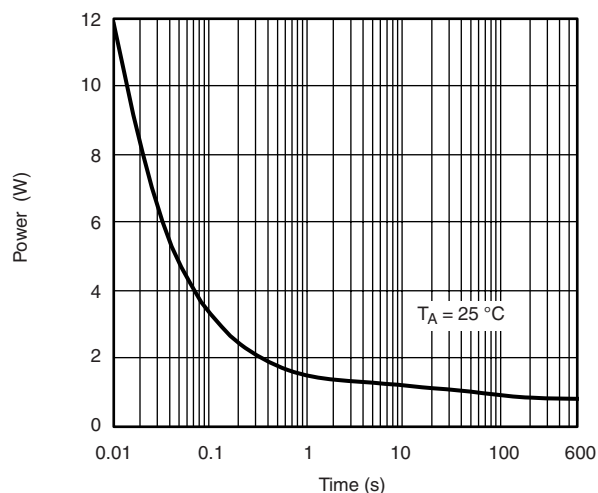
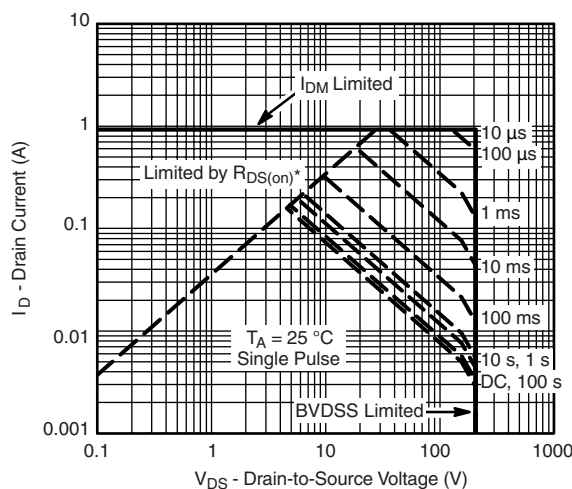
Capacitance



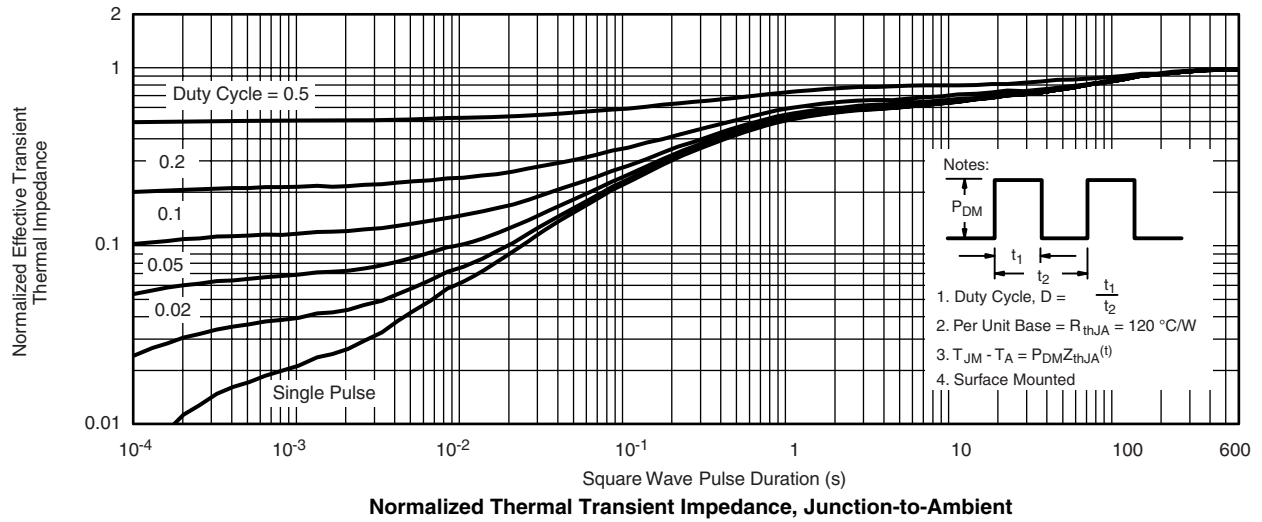
Gate Charge



On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power*** $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified**Safe Operating Area**

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg273240.



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.